

Title (en)

Electronic component and method for manufacturing electronic component

Title (de)

Elektronische Komponente und Verfahren zur Herstellung einer elektronischen Komponente

Title (fr)

Composant électronique et procédé de fabrication de composant électronique

Publication

**EP 2779182 A2 20140917 (EN)**

Application

**EP 14160000 A 20140314**

Priority

- US 201313804857 A 20130314
- CN 201310109345 A 20130329
- CN 201410050474 A 20140213

Abstract (en)

An electronic component includes a magnetic core member (1), a winding (2) and a magnetic exterior body (3). The magnetic core member has a flat base and a core. The flat base has a top surface, a bottom surface, a first side surface and a second side surface opposite to the first side surface. The core is located on the top surface of the flat base. A winding has an edgewise coil and two non-wound flat wires that extend from the edgewise coil. A magnetic exterior body covers at least the core and the edgewise coil. The two non-wound flat wires continuously extend along the top surface, the first side surface, the bottom surface and the second side surface of the flat base in this order. The two non-wound flat wires located on the bottom surface work as electrodes.

IPC 8 full level

**H01F 17/04** (2006.01); **H01F 27/28** (2006.01); **H01F 27/30** (2006.01)

CPC (source: EP)

**H01F 17/045** (2013.01); **H01F 27/2847** (2013.01); **H01F 27/2852** (2013.01); **H01F 27/292** (2013.01); **H01F 27/306** (2013.01); **H01F 2017/046** (2013.01); **H01F 2017/048** (2013.01)

Cited by

CN115206644A; EP3125256A1; US10617006B2; EP3249661A1; US10032558B2; US11107629B2; EP3133618A1; EP3188202A1; EP3783631A1; EP2996124A1; EP3605571A1; EP3985694A1; US10786932B2; US11312045B2; EP3036748B1

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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**EP 14160000 A 20140314**; EP 21170000 A 20140314; EP 24161633 A 20140314